

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











Vishay Siliconix

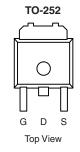
P-Channel 40-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
- 40	0.013 at V _{GS} = - 10 V	- 60 ^a		
	0.022 at V _{GS} = - 4.5 V	- 48		

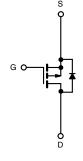
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature





Drain Connected to Tab



P-Channel MOSFET

Ordering Information: SUD50P04-13L-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	5 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 40	V	
Gate-Source Voltage		V _{GS} ± 20		- V	
0 11 D 1 O 1h	T _C = 25 °C	1	- 60 ^c		
Continuous Drain Current ^b	T _C = 100 °C	l _D	- 43		
Pulsed Drain Current		I _{DM}	- 100		
Continuous Source Current (Diode Conduction)		I _S	- 60 ^c		
Avalanche Current	. 04	I _{AS}	- 40		
Avalanche Energy,	L = 0.1 mH	E _{AS}	80	mJ	
b. b b	T _C = 25 °C	В	93.7 ^b	W	
Maximum Power Dissipation ^b	T _A = 25 °C	P _D	3 ^a		
Operating Junction and Storage Temperature Range	·	T_J, T_{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian una livration ta Ambrianta	t ≤ 10 sec	R _{thJA}	15	18	°C/W
Maximum Junction-to-Ambient ^a	Steady State		40	50	
Maximum Junction-to-Case (Drain)		R_{thJC}	1.3	1.8	

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.
- b. Calculated based on maximum allowed Junction Temperature. Package limitation current is 50 A.

SUD50P04-13L

Vishay Siliconix

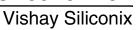


SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static	<u> </u>			1		1	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$	- 40			V	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	·	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Droin Current		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$		- 1			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			- 50	μΑ	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 50			Α	
Drain-Source On-State Resistance ^a		V _{GS} = - 10 V, I _D = - 30 A		0.0105	0.013		
	r _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.020		
		V _{GS} = - 4.5 V, I _D = - 20 A		0.017	0.022		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 30 A	15			S	
Dynamic ^b							
Input Capacitance	C _{iss}			3120		pF	
Output Capacitance	C _{oss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		440			
Reverse Transfer Capacitance	C _{rss}			320			
Gate Resistance	R_g	f = 1 MHz		4.3		Ω	
Total Gate Charge ^c	Qg			63	95		
Gate-Source Charge ^c	Q_{gs}	V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 50 A		13		nC	
Gate-Drain Charge ^c	Q_{gd}			16			
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	$V_{DD} = -20 \text{ V}, R_L = 0.4 \Omega$ $I_D \cong -50 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		18	30	ns	
Turn-Off Delay Time ^c	t _{d(off)}			60	90		
Fall Time ^c	t _f			47	70		
Drain-Source Body Diode Characteristic	s			•			
Pulse Current	I _{SM}				- 100		
Forward Voltage ^a	V_{SD}	I _F = - 50 A, V _{GS} = 0 V		- 1.0	- 1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 50 A, di/dT = 100 A/μs		36	55	ns	

Notes:

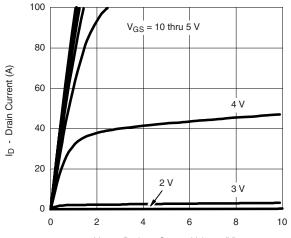
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

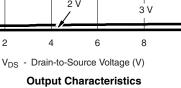
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

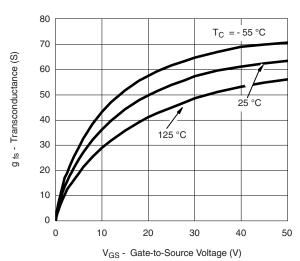




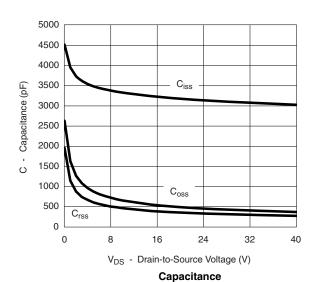
TYPICAL CHARACTERISTICS 25 °C unless noted





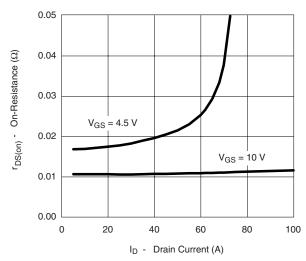


Transconductance

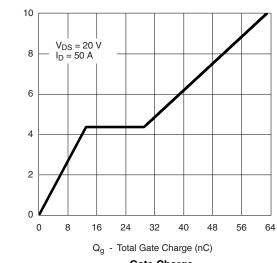


100 80 I D - Drain Current (A) 60 40 T_C = 125 °C 20 25 °C 55 °C 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5.0

V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



On-Resistance vs. Drain Current



V GS - Gate-to-Source Voltage (V)

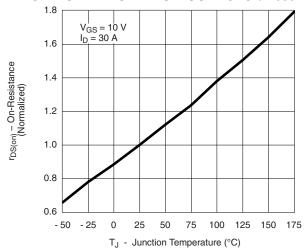
Gate Charge

SUD50P04-13L

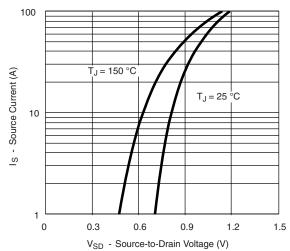
Vishay Siliconix





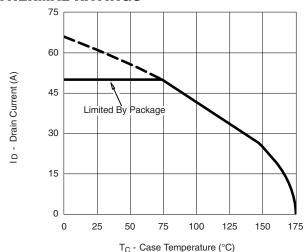


On-Resistance vs. Junction Temperature

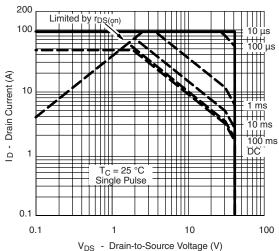


Source-Drain Diode Forward Voltage

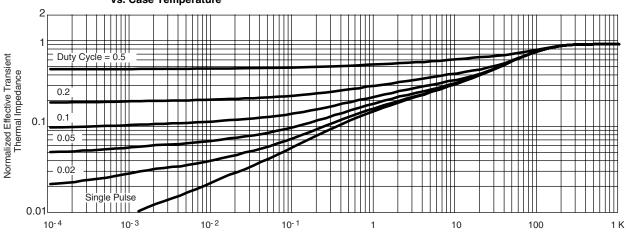
THERMAL RATINGS



Maximum Avalanche Drain Current vs. Case Temperature



Safe Operating Area

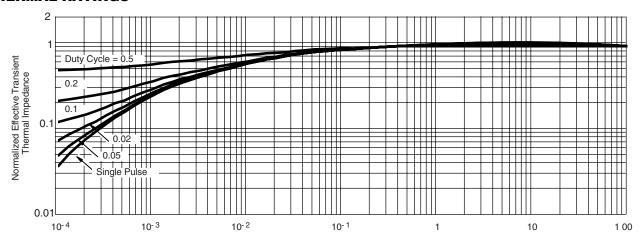


Square Wave Pulse Duration (sec)
Normalized Thermal Transient Impedance, Junction-to-Ambient



Vishay Siliconix

THERMAL RATINGS



Square Wave Pulse Duration (sec)
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?73009



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.

Document Number: 91000 Revision: 18-Jul-08